

**PATENT APPLICATION TRANSMITTAL LETTER**  
(Small Entity)

Docket No.  
879.1.004

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith for filing under 35 U.S.C. 111 and 37 C.F.R. 1.53 is the patent application of:

**Kin P. Cheung**

For: **PROCESSES FOR HERMETICALLY PACKAGING WAFER LEVEL MICROSCOPIC STRUCTURES**

Enclosed are:

- ☒ Certificate of Mailing with Express Mail Mailing Label No. **EV026600038US**  
☒ **Nine (9)** sheets of drawings.  
☐ A certified copy of a \_\_\_\_\_ application.  
☒ Declaration ☒ Signed. ☐ Unsigned.  
☒ Power of Attorney  
☒ Information Disclosure Statement  
☐ Preliminary Amendment  
☐ \_\_\_\_\_ Verified Statement(s) to Establish Small Entity Status Under 37 C.F.R. 1.9 and 1.27.  
☐ Other:

22581 U.S. PTO  
10/691029  
102203

**CLAIMS AS FILED**

For	#Filed	#Allowed	#Extra	Rate	Fee
<b>Total Claims</b>	26	- 20 =	6	x \$9.00	\$54.00
<b>Indep. Claims</b>	5	- 3 =	2	x \$43.00	\$86.00
<b>Multiple Dependent Claims (check if applicable)</b> <input type="checkbox"/>					\$0.00
<b>BASIC FEE</b>					\$385.00
<b>TOTAL FILING FEE</b>					\$525.00

- ☒ A check in the amount of **\$525.00** to cover the filing fee is enclosed.  
☒ The Director is hereby authorized to charge and credit Deposit Account No. **23-0510** as described below.  
☐ Charge the amount of \_\_\_\_\_ as filing fee.  
☒ Credit any overpayment.  
☒ Charge any additional filing fees required under 37 C.F.R. 1.16 and 1.17.  
☐ Charge the issue fee set in 37 C.F.R. 1.18 at the mailing of the Notice of Allowance, pursuant to 37 C.F.R. 1.311(b).

Dated: **October 22, 2003**

*Kenneth Watov*  
Signature

**Kenneth Watov, Esq.**  
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cc:

**CERTIFICATE OF MAILING BY "EXPRESS MAIL" (37 CFR 1.10)**

Applicant(s): Kin P. Cheung

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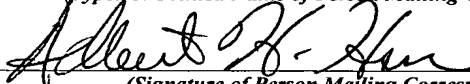
Serial No.  
(Unknown)Filing Date  
(Filed Herewith)Examiner  
(Unknown)Group Art Unit  
(Unknown)Invention: **PROCESSES FOR HERMETICALLY PACKAGING WAFER LEVEL MICROSCOPIC STRUCTURES**

I hereby certify that the following correspondence:

New Patent Application and Corresponding Filing Papers

*(Identify type of correspondence)*

is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on

October 22, 2003*(Date)*Albert H. Hsu*(Typed or Printed Name of Person Mailing Correspondence)**(Signature of Person Mailing Correspondence)*EV026600038US*("Express Mail" Mailing Label Number)***Note: Each paper must have its own certificate of mailing.**